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Renesas Electronics Corporation

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User's Manual

SuperH™ Family E10A-USB Emulator

Additional Document for User's Manual Supplementary Information on Using the SH7750

Renesas Microcomputer Development Environment System
SuperH™ Family / SH7750 Series
E10A-USB for SH7750
HS7750KCU01HE

Renesas Electronics
www.renesas.com

Rev.2.0 2007.03

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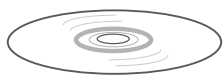
Contents

Section 1 Connecting the Emulator with the User System

1.1 Components of the Emulator

The E10A-USB emulator supports the SH7750 and SH7750S. Table 1.1 lists the components of the emulator.

Table 1.1 Components of the Emulator

Classification	Component	Appearance	Quantity	Remarks
Hardware	Emulator box		1	HS0005KCU01H: Depth: 65.0 mm, Width: 97.0 mm, Height: 20.0 mm, Mass: 72.9 g or HS0005KCU02H: Depth: 65.0 mm, Width: 97.0 mm, Height: 20.0 mm, Mass: 73.7 g
	User system interface cable		1	14-pin type: Length: 20 cm, Mass: 33.1 g
	USB cable		1	Length: 150 cm, Mass: 50.6 g
Software	SH7750 E10A-USB emulator setup program, SuperH™ Family E10A-USB Emulator User's Manual, Supplementary Information on Using the SH7750*, and Test program manual for HS0005KCU01H and HS0005KCU02H		1	HS0005KCU01SR, HS0005KCU01HJ, HS0005KCU01HE, HS7750KCU01HJ, HS7750KCU01HE, HS0005TM01HJ, and HS0005TM01HE (provided on a CD-R)

Note: Additional document for the MPUs supported by the emulator is included. Check the target MPU and refer to its additional document.

1.2 Connecting the E10A-USB Emulator with the User System

To connect the E10A-USB emulator (hereinafter referred to as the emulator), the H-UDI port connector must be installed on the user system to connect the user system interface cable. When designing the user system, refer to the recommended circuit between the H-UDI port connector and the MCU. In addition, read the E10A-USB emulator user's manual and hardware manual for the related device.

1.3 Installing the H-UDI Port Connector on the User System

Table 1.2 shows the recommended H-UDI port connectors for the emulator.

Table 1.2 Recommended H-UDI Port Connectors

Connector	Type Number	Manufacturer	Specifications
14-pin connector	2514-6002	Minnesota Mining & Manufacturing Ltd.	14-pin straight type

Note: Do not place any components within 3 mm of the H-UDI port connector.

1.4 Pin Assignments of the H-UDI Port Connector

Figure 1.1 shows the pin assignments of the H-UDI port connector.

Note: Note that the pin number assignments of the H-UDI port connector shown on the following pages differ from those of the connector manufacturer.

Pin No.	Signal		Input/ Output*1	SH7750 Pin No. BGA256	SH7750 Pin No. HQFP208	Note
1	TCK		Input	A-5	198	
2	/TRST	*2	Input	C-4	200	
3	TDO		Output	A-6	194	
4	/ASEBRK BRKACK	*2	Output	B-7	193	
5	TMS		Input	B-6	197	
6	TDI		Input	B-5	199	
7	/RESETP	*2	Output	B-1	2	User reset
8	N.C.	*5	—	—	—	
9	GND		—	—	—	
11	UVCC	*4	Output	—	—	
10, 12, and 13	GND		—	—	—	
14	GND	*3	Output	—	—	

Notes: 1. Input to or output from the user system.
2. The slash (/) means that the signal is active-low.
3. The emulator monitors the GND signal of the user system and detects whether or not the user system is connected.
4. If the VccQ pin is not connected to the UVCC, the I/O voltage of the user system interface will be fixed to 3.3 V.
5. This pin can be connected to GND.

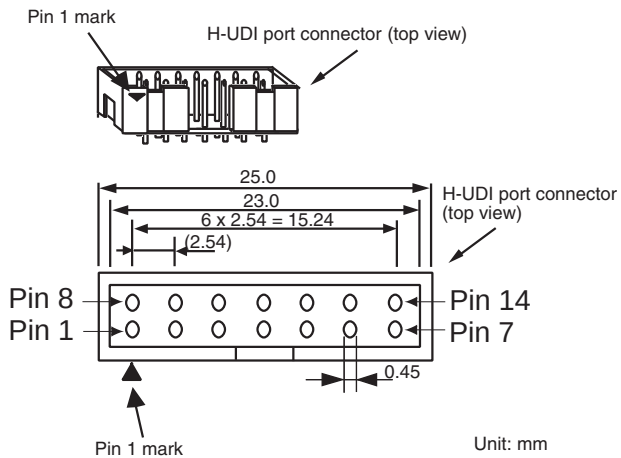


Figure 1.1 Pin Assignments of the H-UDI Port Connector

1.5 Recommended Circuit between the H-UDI Port Connector and the MPU

1.5.1 Recommended Circuit (14-Pin Type)

Figure 1.2 shows a recommended circuit for connection between the H-UDI port connector and the MPU when the emulator is in use. Figure 1.3 shows a circuit for connection when UVCC is not connected.

Notes: 1. Do not connect anything to the N.C. pins of the H-UDI port connector.

2. When a network resistance is used for pull-up, it may be affected by a noise. Separate TCK from other resistances.
3. The pattern between the H-UDI port connector and the MPU must be as short as possible. Do not connect the signal lines to other components on the board.
4. When the power supply of the user system is turned off, supplying VccQ of the user system to the UVCC pin reduces the leakage current from the emulator to the user system. A level shifter that is activated by the internal power supply or user power supply (changed by the switch) is installed in the interface circuit of the emulator. If the user power is supplied to the UVCC pin, the level shifter is not activated as long as no user power is supplied. When the power supply of the user system is turned off, no current flows from the user interface. The I/O voltage level of the user system interface can be the same as that of the VccQ. To operate the emulator with low voltage (lower than 3.3 V), the VccQ must be supplied to the UVCC pin. Make the emulator's switch settings so that the VccQ will be supplied (SW2 = 1 and SW3 = 1) (as shown in figure 1.2).
5. The resistance values shown in figures 1.2 and 1.3 are recommended.
6. For the pin processing in cases where the emulator is not used, refer to the hardware manual of the related MPU.

When the circuit is connected as shown in figure 1.2, the switches of the emulator are set as SW2 = 1 and SW3 = 1. For details, refer to section 3.8, Setting the DIP Switches, in the SuperH™ Family E10A-USB Emulator User's Manual.

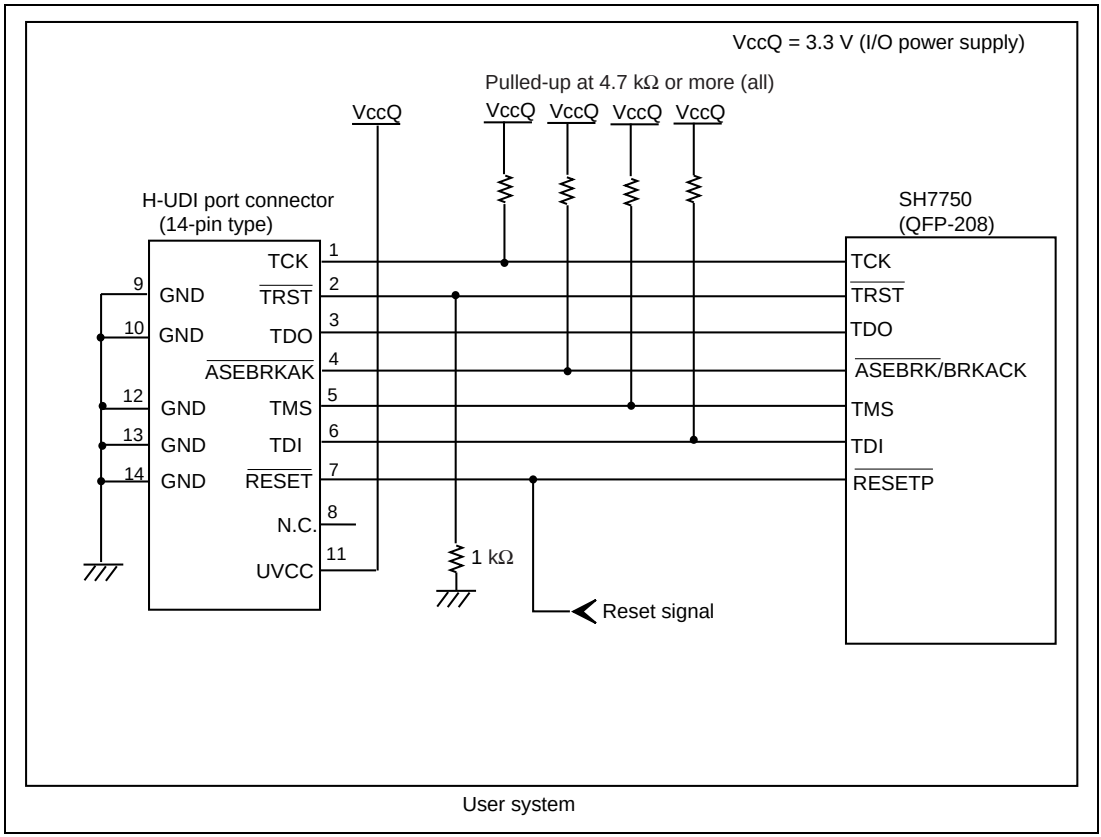


Figure 1.2 Recommended Circuit for Connection between the H-UDI Port Connector and MPU when the Emulator is in Use (14-Pin Type UVCC Connected)

When the circuit is connected as shown in figure 1.3, the switches of the emulator are set as SW2 = 0 and SW3 = 1. For details, refer to section 3.8, Setting the DIP Switches, in the SuperH™ Family E10A-USB Emulator User's Manual.

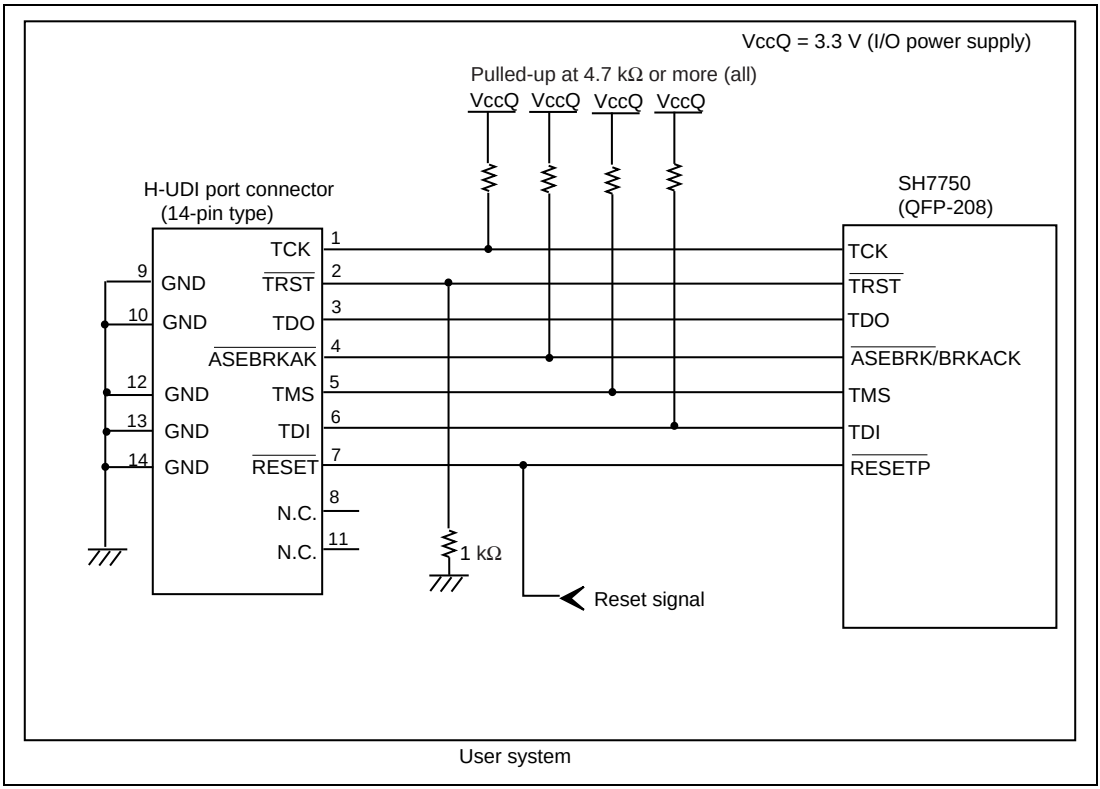


Figure 1.3 Circuit for Connection between the H-UDI Port Connector and MPU when the Emulator is in Use (14-Pin Type UVCC Not Connected*)

Note: When UVCC is not connected and the user system is turned off, note that the leakage current flows from the emulator to the user system.

Section 2 Specifications of the Software when Using the SH7750

2.1 Differences between the SH7750, SH7750S, and the Emulator

1. When the emulator system is initiated, it initializes the general registers and part of the control registers as shown in table 2.1. When the emulator is initiated from the workspace, a value to be entered is saved in a session.

Table 2.1 Register Initial Values at Emulator Link Up

Register	Emulator at Link Up
R0 to R14	H'00000000
R15 (SP)	H'00000000
R0_BANK to R7_BANK	H'00000000
PC	H'A0000000
SR	H'700000F0
GBR	H'00000000
VBR	H'00000000
MACH	H'00000000
MACL	H'00000000
PR	H'00000000
DBR	H'00000000
SGR	H'00000000
SPC	H'00000000
SSR	H'000000F0
FPUL	H'00000000
FPSCR	H'00040001
FR0 to FR15	H'00000000
XF0 to XF15	H'00000000

2. The emulator uses the H-UDI; do not access the H-UDI.

3. Low-Power States (Sleep, Standby, and Module Standby)

   For low-power consumption, the SH7750 and SH7750S have sleep, standby, and module standby modes.

   The sleep and standby modes are switched using the SLEEP instruction. When the emulator is used, the sleep mode can be cleared by either normal clearing or by the satisfaction of a break condition (including BREAK key input). In the latter case, the user program breaks. The standby mode can be cleared with the normal clearing function or BREAK key input, and after the standby mode is cleared, the user program operates correctly. Note, however, that if a command has been entered in standby mode or module standby mode, no commands can be used from the emulator after the standby mode is cleared.

Note: After the sleep mode is cleared by a break, execution restarts at the instruction following the SLEEP instruction.
If the memory is accessed or modified in sleep mode, the sleep mode is cleared and execution starts at the instruction following the SLEEP instruction.
Although the SH7750S supports the hardware standby function, if the emulator enters the hardware standby mode, a TIMEOUT error will occur.
When the SLEEP instruction is executed by a step command and [Step…] in the [Run] menu is used, set [Rate] as 6. If 5 or lower value is set, a communication timeout error will occur.

4. Reset Signals

   The SH7750 and SH7750S reset signals are only valid during emulation started with clicking the GO or STEP-type button. If these signals are enabled on the user system in command input wait state, they are not sent to the SH7750 or SH7750S.

Note: Do not break the user program when the /RESET or /BREQ signal is being low or the /RDY signal is being high. A TIMEOUT error will occur. If the /BREQ signal is fixed to low or the /RDY signal is fixed to high during break, a TIMEOUT error will occur at memory access.

5. Direct Memory Access Controller (DMAC)

   The DMAC operates even when the emulator is used. When a data transfer request is generated, the DMAC executes DMA transfer.

6. Memory Access during User Program Execution

   When a memory is accessed from the memory window, etc. during user program execution, the user program is resumed after it has stopped in the emulator to access the memory. Therefore, realtime emulation cannot be performed.

The stopping time of the user program is as follows:

Environment:

Host computer: 1 GHz (Pentium® III)
OS: Windows® 2000
SH7750: 200 MHz (CPU clock)
JTAG clock: 20 MHz

When a one-byte memory is read from the command-line window, the stopping time will be about 45 ms.

7. Interrupt

When the NMIB bit in the ICR register is 1, the NMI interrupt is accepted during break and the program is executed from the NMI interrupt vector. If the program cannot return normally from the NMI interrupt routine or the value in the general-purpose register is not guaranteed, a communication timeout error will occur.

8. Memory Access during User Program Break

The emulator can download the program for the flash memory area (refer to section 6.22, Download Function to the Flash Memory Area, in the SuperH™ Family E10A-USB Emulator User's Manual). Other memory write operations are enabled for the RAM area. Therefore, an operation such as memory write or BREAKPOINT should be set only for the RAM area. When the memory area can be written by the MMU, do not perform memory write, BREAKPOINT break, or downloading.

9. Cache Operation during User Program Break

When cache is enabled, the emulator accesses the memory by the following methods:

- At memory write: Writes through the cache, then writes to the memory.
- At memory read: Does not change the cache write mode that has been set.

Therefore, when memory read or write is performed during user program break, the cache state will be changed.

When the half of operand cache is used as an internal RAM and memory fill is performed in this area, the verify option must be disabled. Memory fill is not performed correctly if the verify option is enabled.

10. Loading Sessions

Information in [JTAG clock] of the [Configuration] dialog box cannot be recovered by loading sessions. Thus the TCK value will be 0.625 MHz.

11. [IO] Window

- Display and modification

  When [End] is set in the [UBC Mode] list box of the [Configuration] dialog box, do not change values of the User Break Controller because it is used by the emulator.

  For each watchdog timer register, there are two registers to be separately used for write and read operations.

Table 2.2 Watchdog Timer Register

Register Name	Usage	Register
WTCSR(W)	Write	Watchdog timer control/status register
WTCNT(W)	Write	Watchdog timer counter
WTCSR(R)	Read	Watchdog timer control/status register
WTCNT(R)	Read	Watchdog timer counter

- The watchdog timer operates only when the user program is executed. Do not change the value of the frequency change register in the [IO] window or [Memory] window.
- The internal I/O registers can be accessed from the [IO] window. However, note the following when accessing the SDMR register of the bus-state controller. Before accessing the SDMR register, specify addresses to be accessed in the I/O-register definition file (SH7750.IO) and then activate the High-performance Embedded Workshop. After the I/O-register definition file is created, the MPU's specification may be changed. If each I/O register in the I/O-register definition file differs from addresses described in the hardware manual, change the I/O-register definition file according to the description in the hardware manual. The I/O-register definition file can be customized depending on its format. Note that, however, the emulator does not support the bit-field function.

Note: As default, SDMR2 and SDMR3 are specified in the I/O-register definition file as the SDMR registers in areas 2 and 3, respectively.
When the SH7750S is used, the IPRD register is not displayed in the [IO] window. To get it to display, edit the I/O-register definition file (SH7750.IO) as follows and start the HEW:
In SH7750.IO, locate 'IPRC = 0xFFD0000C W A'. Under this, add 'IPRD = 0xFFD00010 W A' and save the file.

- Verify

  In the [IO] window, the verify function of the input value is disabled.

12. Illegal Instructions

If illegal instructions are executed by STEP-type commands, the emulator cannot go to the next program counter.

2.2 Specific Functions for the Emulator when Using the SH7750

2.2.1 Break Condition Functions

In addition to BREAKPOINT functions, the emulator has Break Condition functions. Five types of conditions can be set under Break Condition 1, 2, 3, 4, 5. Table 2.3 lists these conditions of Break Condition.

Table 2.3 Types of Break Conditions

Break Condition Type	Description
Address bus condition (Address)	Breaks when the SH7750 or SH7750S address bus value or the program counter value matches the specified value.
Data bus condition (Data)	Breaks when the SH7750 or SH7750S data bus value matches the specified value. Byte, word, or longword can be specified as the access data size.
ASID condition (ASID)	Breaks when the SH7750 or SH7750S ASID value matches the specified condition.
Bus state condition (Bus State)	There are two bus state condition settings: Read/write condition: Breaks in the read or write cycle of the SH7750 or SH7750S. Bus state condition: Breaks when the operating state in an SH7750 or SH7750S bus cycle matches the specified condition.
LDTLB instruction break condition	Breaks when the SH7750 or SH7750S executes the LDTLB instruction.
Internal I/O break condition	Breaks when the SH7750 or SH7750S accesses the internal I/O.

Note: For the window function or command-line syntax, refer to the online help.

Table 2.4 lists the combinations of conditions that can be set under Break Condition 1, 2, 3, 4, 5.

Table 2.4 Dialog Boxes for Setting Break Conditions

	Dialog Box		
	[Break Condition 1] Dialog Box	**[Break Condition 2, 3, 4] Dialog Box**	**[Break Condition 5] Dialog Box**
Address bus condition (Address)	O	O	X
Data bus condition (Data)	O	X	X
ASID condition (ASID)	O	O	X
Read/write specification	O	O	X
Data access	O	O	X
Before/after execution	O	O	X
Sequential break	O	O	X
LDTLB instruction break	X	X	O
Internal I/O access break	X	X	O

Note: O: Can be set in the dialog box.
X: Cannot be set in the dialog box.

Notes: 1. If the BL bit of the SR register is 1, do not use BREAKPOINTs.
2. If a break is specified for an address that is close to an address whose instruction generates a manual reset, a manual reset may be generated instead of a break. Therefore, to ensure the performance of a break, specify a break for an address that is four addresses before the address whose instruction generates an exception.

The emulator has sequential break functions. Table 2.5 shows the sequential break conditions.

Table 2.5 Sequential Break Conditions

Break Condition	Description
Sequential break condition 2-1	Program is halted when Break Condition 2 and Break Condition 1 are satisfied in that order. Break Condition 2,1 should be set.
Sequential break condition 3-2-1	Program is halted when Break Condition 3, Break Condition 2, and Break Condition 1 are satisfied in that order. Break Condition 3,2,1 should be set.
Sequential break condition 4-3-2-1	Program is halted when Break Condition 4, Break Condition 3, Break Condition 2, and Break Condition 1 are satisfied in that order. Break Condition 4,3,2,1 should be set.

2.2.2 Trace Functions

The emulator does not support the AUD function.

Table 2.6 shows the internal trace functions.

Table 2.6 Internal Trace Functions

Function	Description
Branch instruction trace	Traces and displays the branch instructions. The branch source address and branch destination address for the eight latest branch instructions are displayed. There are three kinds of branch instruction trace: • Normal branch instruction trace Traces and displays the normal branch instructions. The normal branch instructions are the BF, BF/S, BT/S, BRA, BRAF, and JMP instructions. To use this function, select the [Acquire normal branch instruction trace] check box of the [Branch trace] page. • Subroutine branch instruction trace Traces and displays the subroutine branch instructions. The subroutine branch instructions are the BSR, BSRF, JSR, and RTS instructions. To use this function, select the [Acquire subroutine branch instruction trace] check box of the [Branch trace] page • Exception branch instruction trace Traces and displays the exception branch instruction. The exception branch instruction is the RTE instruction. In addition, all the exception and interrupt operations are traced. To use this function, select the [Acquire exceptional branch instruction trace] check box of the [Branch trace] page.
Continuous trace	Acquires the trace information continuously. This is called continuous trace. For the branch instruction trace, eight-branch information can be repeatedly acquired a maximum of four times. Select the [Acquire continuous trace] check box of the [Branch trace] page. If continuous trace is selected, realtime trace cannot be performed.
Internal I/O trace	Traces and displays the address and data that access the internal I/O area. To use this function, select the [Get trace information of internal I/O Area] radio button in the [Break Condition 5] dialog box and the [Acquire continuous trace] check box of the [Branch trace] page.
LDTLB instruction execution trace	Traces and displays the address that executes the LDTLB instruction. To use this function, select the [Get trace information of LDTLB instruction] radio button in the [Break Condition 5] dialog box and the [Acquire continuous trace] check box of the [Branch trace] page.

1. Notes on the [Trace] Window

   (1) If an interrupt is generated at the program execution start or end, including a step operation, the emulator address may be acquired. In such a case, the following message will be displayed. Ignore this address because it is not a user program address.

   *** EML ***

   (2) If a TLB error occurs while acquired trace information is displayed, the following error message will be displayed.

Figure 2.1 Message Box for Clearing a TLB Error

   After a TLB error, trace acquisition cannot be performed.

   (3) When MMU settings are modified or when a user program is changed between GO command completion and trace display, the displayed mnemonics or operand may not be correct.

   (4) If a completion-type exception occurs during exception branch acquisition, the next address to the address in which an exception occurs is acquired.

   (5) When a user interrupt is enabled by the INTERRUPT command during the emulator command wait state or user program execution, an interrupt that is generated at the program execution start or end, including a step operation, can be traced in realtime.

2. Notes on Setting the [Trace Acquisition] Window

   (1) When the [Acquire continuous trace] check box is selected, do not perform memory access during emulation.

   (2) When internal I/O trace or LDTLB instruction trace is performed, select the [Acquire continuous trace] check box.

   (3) When the [Acquire continuous trace] check box is selected, 32 trace information data can be acquired. In this case, however, since the user program stops at constant intervals, the processing speed is decreased compared with the case where the [Acquire continuous trace] check box is not selected.

(4) Trace information cannot be acquired for the following branch instructions:
- The BF and BT instructions whose displacement value is 0
- Branch to H'A0000000 by reset

(5) When the [Acquire continuous trace] check box is selected, and when either the [Get trace information of internal I/O area] radio button (internal I/O trace enabled) or the [Get trace information of LDTLB instruction] radio button is selected (LDTLB instruction trace enabled) with the [Break Condition 5] dialog box,
- An internal I/O trace cannot be made with the Step In command.
- The LDTLB instruction and internal I/O trace cannot be performed with the Step Over command.

(6) Do not use the continuous trace for a program in which an SGR value is referred to with the interrupt handler. In the emulator, the contents of the SGR register are lost when the user program breaks. Since the user program execution stops at constant intervals while the continuous trace is selected, the contents of the SGR register will be lost.

(7) When continuous trace is used, do not enable user interrupt by the INTERRUPT command during the emulator command wait state or user program execution.

2.2.3 Notes on Using the JTAG Clock (TCK)

Set the JTAG clock (TCK) frequency to lower than the frequency of the SH7750 or SH7750S peripheral module clock (CKP).

2.2.4 Notes on Setting the [Breakpoint] Dialog Box

1. When an odd address is set, the next lowest even address is used.
2. A BREAKPOINT is accomplished by replacing instructions. Accordingly, it can be set only to the internal RAM area. However, a BREAKPOINT cannot be set to the following addresses:
   - An address whose memory content is H'003B
   - An area other than the CS0 to CS6 areas and the internal RAM area
   - An instruction in which Break Condition 4 is satisfied
   - A slot instruction of a delayed branch instruction

   In addition, do not perform memory write, BREAKPOINT, or download even if the memory space can only be written by the MMU.
3. During step operation, a BREAKPOINT is disabled.
4. Conditions set at Break Condition 3 are disabled when an instruction to which a BREAKPOINT has been set is executed. Do not set a BREAKPOINT to an instruction in which Break Condition 3 is satisfied.

5. When execution resumes from the address where a BREAKPOINT is specified, single-step operation is performed at the address before execution resumes. Therefore, realtime operation cannot be performed.
6. When a BREAKPOINT is set to the slot instruction of a delayed branch instruction, the PC value becomes an illegal value. Accordingly, do not set a BREAKPOINT to the slot instruction of a delayed branch instruction.
7. When the [Normal] option is selected in the [Memory area] group box in the [General] page of the [Configuration] dialog box, a BREAKPOINT is set to a physical address or a virtual address according to the SH7750 or SH7750S MMU state during command input when the VPMAP_SET command setting is disabled. The ASID value of the SH7750 or SH7750S PTEH register during command input is used. When VPMAP_SET command setting is enabled, a BREAKPOINT is set to a physical address into which address translation is made according to the VP_MAP table. However, for addresses out of the range of the VP_MAP table, the address to which a BREAKPOINT is set depends on the SH7750 or SH7750S MMU state during command input. Even when the VP_MAP table is modified after BREAKPOINT setting, the address translated at BREAKPOINT setting is valid.
8. When the [Physical] option is selected in the [Memory area] group box in the [General] page of the [Configuration] dialog box, a BREAKPOINT is set to a physical address. A BREAKPOINT is set after disabling the SH7750 or SH7750S MMU during program execution. After setting, the MMU is returned to the original state. When a break occurs at the corresponding virtual address, the cause of termination displayed in the status bar and the [System Status] window is ILLEGAL INSTRUCTION, not BREAKPOINT.
9. When the [Virtual] option is selected in the [Memory area] group box in the [General] page of the [Configuration] dialog box, a BREAKPOINT is set to a virtual address. A BREAKPOINT is set after enabling the SH7750 or SH7750S MMU during program execution. After setting, the MMU is returned to the original state. When an ASID value is specified, the BREAKPOINT is set to the virtual address corresponding to the ASID value. The emulator sets the BREAKPOINT after rewriting the ASID value to the specified value, and returns the ASID value to its original value after setting. When no ASID value is specified, the BREAKPOINT is set to a virtual address corresponding to the ASID value at command input.
10. If a TLB error occurs during virtual address setting, the following message box will be displayed.

Figure 2.2 Message Box for Clearing a TLB-Error

If a program is executed again without clearing the BREAKPOINT set at the address in which the TLB error occurs, a TLB error will occur again. Accordingly, clear the BREAKPOINT before execution.

11. An address (physical address) to which a BREAKPOINT is set is determined when the BREAKPOINT is set. Accordingly, even if the VP_MAP table is modified after BREAKPOINT setting, the BREAKPOINT address remains unchanged. When a BREAKPOINT is satisfied with the modified address in the VP_MAP table, the cause of termination displayed in the status bar and the [System Status] window is ILLEGAL INSTRUCTION, not BREAKPOINT.
12. When a BREAKPOINT is set to the cacheable area, the cache block containing the BREAKPOINT address is filled immediately before and after user program execution.
13. While a BREAKPOINT is set, the contents of the instruction cache are disabled at execution completion.
14. If an address of a BREAKPOINT cannot be correctly set in the ROM or flash memory area, a mark ● will be displayed in the [BP] area of the address on the [Source] or [Disassembly] window by refreshing the [Memory] window, etc. after Go execution. However, no break will occur at this address. When the program halts with the break condition, the mark ● disappears.

2.2.5 Notes on Setting the [Break Condition] Dialog Box and the BREAKCONDITION_SET Command

1. When [Go to cursor], [Step In], [Step Over], or [Step Out] is selected, the settings of Break Condition 4 are disabled.
2. Break Condition 4 is disabled when an instruction to which a BREAKPOINT has been set is executed. Accordingly, do not set a BREAKPOINT to an instruction which satisfies Break Condition 4.
3. When a Break Condition is satisfied, emulation may stop after two or more instructions have been executed.

4. If a PC break address condition is set to the slot instruction after a delayed branch instruction, user program execution cannot be terminated before the slot instruction execution; execution stops before the branch destination instruction.
5. In the [Configuration] dialog box, if [User] is set while the [UBC mode] list box has been set, Break Condition 5,6 are available.

2.2.6 Performance Measurement Functions

The emulator supports the performance measurement function.

1. Setting the performance measurement conditions

   To set the performance measurement conditions, use the [CPU Performance] dialog box and the PERFORMANCE_SET command. When any line on the [Performance Analysis] window is clicked with the right mouse button, the popup menu is displayed and the [CPU Performance] dialog box is displayed by selecting [Setting].

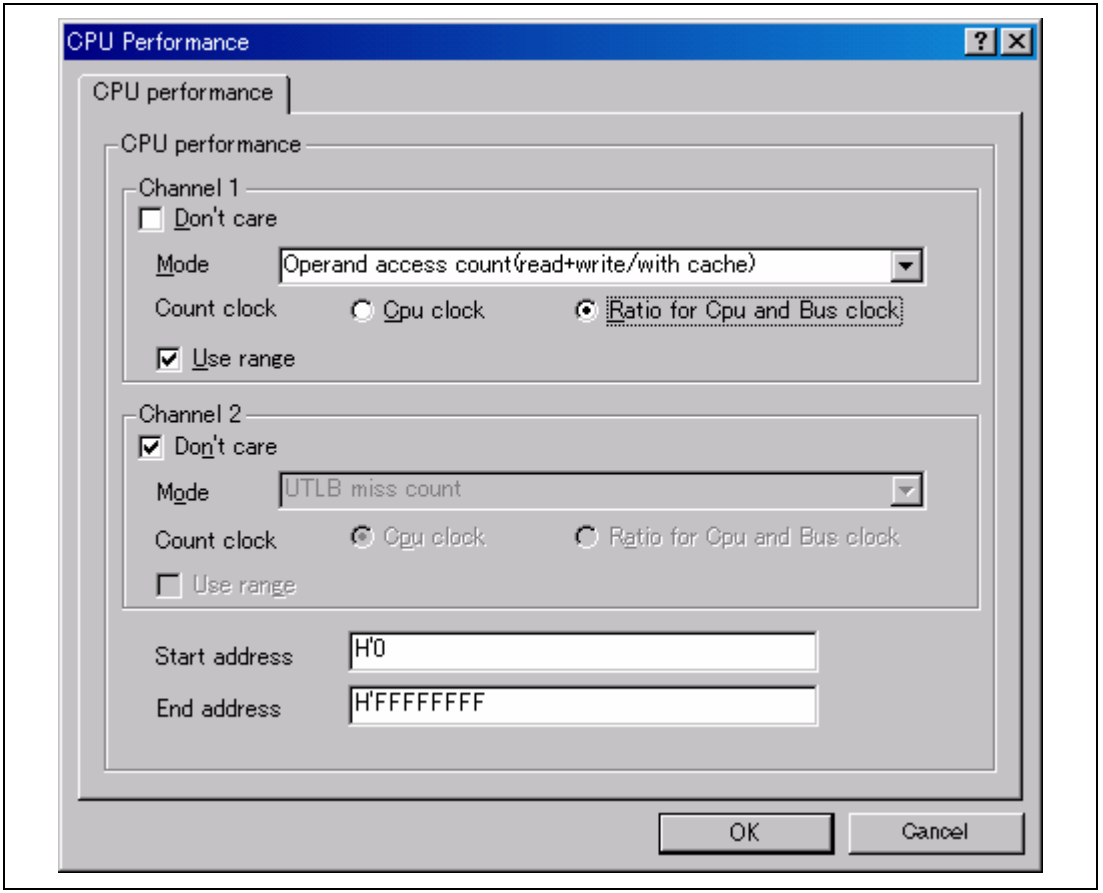


Figure 2.3 [CPU Performance] Dialog Box

Note: For the command line syntax, refer to the online help.

The emulator measures how many times the conditions of the user program specified with the performance analysis function are satisfied. For this function, two events can be measured simultaneously and the following conditions can be specified. When the PC value is set, the original UBC function is not available because the UBC is used to specify the measurement start and end PC values.

(a) Measurement range

One of the following ranges can be specified by either of measurement channels 1 and 2.

1. From the start to the end of the user program execution
2. From the satisfaction of the condition set in [Start address] to the satisfaction of the condition set in [End address]

When the first range is specified, the measurement result includes a several-cycle error for one user program execution. Therefore, do not specify this range when the step is to be executed. In addition, the user program execution stops when continuous trace is used; again, do not specify the first range in this case.

Note: When the range is specified, be sure to select the [Use range] check box, set the measurement start and end conditions for [Start address] and [End address], respectively, and then execute the user program.

(b) Measurement item

Items are measured with [Channel 1 to 2] in the [CPU Performance] dialog box. Maximum two conditions can be specified at the same time. Table 2.7 shows the measurement items (Options in table 2.7 are parameters for <mode> of the PERFORMANCE_SET command. They are displayed for NAME in the [Performance Analysis] window).

Table 2.7 Measurement Items

Event	Keyword	Description
Operand access count (read and write/with cache)	OARW*	The number of times the operand access is performed on the cacheable area when the cache is enabled (both read and write accesses).
Internal RAM operand access count	OARAM	The number of times the internal RAM area is accessed.
All operand access count	OA	The number of all operand accesses.
Internal I/O area access count	IOA	The number of times the internal I/O area is accessed.
Operand cache read and write miss count	DCRW	The number of times operand cache misses occur at data reading or writing.
Instruction cache miss count	EC	The number of times instruction cache misses.
UTLB miss count	DT	The number of times UTLB misses occur at data access.
Instruction TLB miss count (ITLB and UTLB misses)	ET	The number of times UTLB and ITLB misses occur at instruction access.
Instruction fetch count	EF*	The number of times instructions are fetched from the cacheable area when the cache is enabled.
All instruction fetch count	EA	The number of times all instructions are fetched.
Branch instruction execution count	B	The number of times branch instructions are issued (instructions to be counted: BF (other than displacement 0), BF/S and BT (other than displacement 0), BT/S, BRA, BRAF, and JMP).
Branch taken count	BT	The number of times branches are taken (branches to be counted are the same as mode B).
Instruction execution count	E	The number of times instructions are issued.

Table 2.7 Measurement Items (cont)

Event	Keyword	Description
Two-instruction concurrent execution count	E2	The number of times two instructions are issued at the same time.
FPU instruction execution count	EFP	The number of times FPU instruction is issued.
TRAPA instruction execution count	ETR	The number of times the TRAPA instruction is executed.
Interrupt count (normal)	INT	The number of interrupts (generally except for NMI).
Interrupt count (NMI)	NMI	The number of NMI interrupts.
Instruction cache-fill cycle	ECF	The number of instruction cache-fill cycles.
Operand cache-fill cycle	OCF	The number of operand cache-fill cycles.
Elapsed-time cycle	TM	The number of cycles for elapsed time.

Note: For the non-cache operand accesses due to the PREF instruction or TLB.c=0, the correct value cannot be counted.

The events can be counted even in the conditions shown in table 2.8, in addition to the normal count conditions.

Table 2.8 Performance Count Conditions

Event	Count Condition	Target Mode
All count conditions	When the event to be counted up is canceled by an exception.	All
Instruction cache miss count	• Includes instruction fetch for the cache-off area to count the number of times the instruction has not been fetched in one cycle. • When a cache miss occurs during an overrun fetch generated at exception.	EC
TLB miss count	When the TLB miss is canceled by an exception having a higher priority than that of the TLB miss	DT and ET
Instruction fetch count	• When the instruction fetch request by the CPU is accepted. • Does not count when the cache is bypassed from the external bus to supply the instruction to the CPU at instruction cache miss.	EF and EA
Instruction issue count	Counts one when two instructions are issued at the same time.	E
	Counts one to three when instruction fetch exception (instruction address error, instruction TLB miss exception, or instruction TLB protection violation exception) occurs.	E and E2
FPU instruction issue count	• Counts one when two instructions are issued at the same time. • The following shows the FPU instructions: LDS Rm, FPUL, LDS.L @Rm+, FPUL, LDS Rm, FPSCR, LDS.L @Rm+, FPSCR, STS FPUL, Rn, STS.L FPUL, @-Rn, STS FPSCR, Rn, STS.L FPSCR, @-Rn Others: instructions that the instruction code is H'Fxxx	EFP

(c) Counting method

One of the following methods can be specified by each of measurement channels 1 and 2.

1. Counted by the CPU operating clock
2. Counted by the ratio of the CPU operating clock to the bus clock

When the above method 1 is specified, one CPU operating clock cycle is counted as one. When method 2 is specified, the count is incremented by 3, 4, 6, 8, 12, or 24, according to the clock frequency ratio (ratio of the CPU clock to the bus clock). In this case, the execution time can be calculated by the following expression:

T = C x B / 24 (T: Execution time; B: Time of one bus clock cycle; C: Count)

When the ratio of the CPU clock to the bus clock is changed in the user program, it is recommended to select method 2, above, to count the number of cycles.

The following shows examples to measure the performance of the user program by the performance measurement function.

(i) Measuring cache hit ratio

Specify measurement channel 1 to count the cache misses (for data read and write) and specify measurement channel 2 to count operand accesses (read and write) to the cacheable area while the cache is enabled. Specify, with both the channels, the measurement from the start to the end of user program execution.

With the above command settings, the cache miss count and the access count to the cacheable area can be measured, and the cache hit ratio in the executed user program can be obtained.

(ii) Measuring ratio of execution time in specified program area to total execution time

Specify measurement channel 1 to measure the elapsed cycle count from the start to the end of user program execution. Specify measurement channel 2 to measure the elapsed cycle count during execution from the specified start PC to the specified end PC.

With both the channels, the total elapsed cycle and the elapsed cycle for the specified program area can be measured, and the ratio of the execution time in the specified program area to the total execution time can be obtained.

Notes:
1. The counter for performance measurement has 48 bits. A maximum of $2^{48} = 2.8 \times 10^{14}$ counts and 16.3-day cycles (when the CPU operating frequency is 200 MHz) can be measured. If a counter overflow occurs, the count becomes invalid.
2. When performance measurement conditions are set, canceled, or initialized, the settings in the UBC are not guaranteed.
3. Set the same start and end PC values for both channels 1 and 2. If different PC values are set, the last settings become valid.
4. When the start and end PC values are set with this command, the value that has been previously set for UBC becomes invalid.
5. For details on command-line syntax, refer to the online help.

2. Displaying the measured result

   The measured result is displayed in the [Performance Analysis] window or the PERFORMANCE_ANALYSIS command with hexadecimal (32 bits).

Note: If a performance counter overflows as a result of measurement, "********" will be displayed.

3. Initializing the measured result

   To initialize the measured result, select [Initialize] from the popup menu in the [Performance Analysis] window or specify INIT with the PERFORMANCE_ANALYSIS command.

2.2.7 Note on Using the Profile Function

While the profile function is being used, in addition to the description in section 5.8.12 in the SuperH™ Family E10A-USB Emulator User's Manual, the following functions cannot be used.

1. Continuous trace function

   When the profile function is enabled, do not use the continuous trace function that can be used in the internal trace function. The profile data cannot be measured correctly.

2. Internal trace function

   When the profile function is enabled, mode selection of the internal trace is disabled since all items of the internal trace modes are selected in the emulator.

3. Halt function

   When the profile function is enabled, do not use the halt function for the internal trace.

2.2.8 Interrupts

During emulation, any interrupt to the SH7750 or SH7750S can be used. Whether or not to process interrupts during emulator command execution or in command input wait state can be specified.

— When no interrupt is processed during user program execution or in command input wait state

  While the emulator is executing the user program or is in command input wait state, interrupts are not processed generally. However, if an internal interrupt or an edge sensitive external interrupt occurs in command input wait state, the emulator holds the interrupt and executes the interrupt processing routine when the GO command is entered.

— When interrupts are processed during user program execution or in command input wait state

To process the non-maskable interrupt and peripheral module interrupts during emulator command execution and in command input wait state, use the INTERRUPT command. Input the INTERRUPT command into the command line window.

- To process only the non-maskable interrupt
  Specify "nonmask" in the <interrupt_enable> option of the INTERRUPT command.
- To process the non-maskable interrupt and peripheral module interrupts
  Specify "all" in the <interrupt_enable> option of the INTERRUPT command.
- To switch to the mode in which no interrupt is processed:
  Specify "disable" in the <interrupt_enable> option of the INTERRUPT command.

Notes:
1. Check that the interrupt handler operates normally before using this function. In addition, do not execute a non-limited loop or the sleep instruction in the interrupt handler. If the processing of the handler does not end, the emulator generates a Communication Timeout error.
2. When interrupts are accepted during user program execution and emulator command execution state, user interrupt processing is not traced. In this case, continuous trace is not enabled.
3. Use the NOP instruction at the delay slot after the RTE instruction in the interrupt handler.
4. If a user interrupt is inserted while the user program breaks until the processing ends, do not set a BREAKPOINT in the interrupt handler. The emulator may generate a Communication Timeout error. Use the Break Condition function.
5. For details on window function and command-line syntax, refer to the online help.

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